

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC10H02
Package Type :	PDFNWB5x6-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	3.179%
Lead Frame	Copper	7440-50-8	97.3317%	38.5802%
	Fe	7439-89-6	2.4123%	
	P	7723-14-0	0.079%	
	Zn	7440-66-6	0.143%	
	Pb	7439-92-1	0.029%	
	Ag	7440-22-4	0.005%	
Die Attach	Lead	7439-92-1	92.50%	19.4753%
	Tin	7440-31-5	5.00%	
	silver	7440-22-4	2.50%	
Aluminum Ribbon	Aluminum	7429-90-5	99.99%	2.4383%
	others	/	0.01%	
Wire2	Cu	7440-50-8	97.898%	3.3025%
	Pd	7440-05-3	1.98%	
	Au	7440-57-5	0.122%	
Mold Compound	Silica	60676-86-0	85.00%	29.2901%
	Epoxy Resin	85954-11-6	8.50%	
	Phenol Resin	29690-82-2	6.00%	
	Carbon Black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	100.00%	3.7346%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.